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The Analog and Digital Company™



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9P960AFLF

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Customer Support / Technical Support

DESCRIPTION

PC BUFFER

Recommended Application:: Dual DDR zero delay buffer

Product Description/Features:

High performance, low jitter zero delay buffer
I2C for functional and output control
Dual bank 1-6 differential clock distribution
2 separate feedback in & out for input to output synchronization for each bank
Supports up to 4 DDR DIMMs
Supports up to DDRII - 1066MHz
Supports up to DDRIII (1.8V core) - 1333MHz

Generic Part:

[9P960](#)

Category:

[DDR Solutions](#)

PARAMETERS

Temperature	C
Voltage	1.8 V
Package	SSOP 48
Speed	NA
Output Style	
Core Supply Voltage (VDD)	
No. of Outputs	
Min. Output Frequency	
Min. Input Frequency	
Output Supply Voltage (VDDO)	
No. of Inputs	
Input Style	
Max. Output Frequency	
Max. Input Frequency	
Temp. Grade	
Multiplication/Divide Value	
CPU Manufacturer	
Chipset	
Yellow Cover Spec.	
Embedded	
Suggested - Pkg. Voltage	
Temp. Range	

PACKAGE

Package	SSOP 48 (PVG48)
Description	SSOP 300 MIL
Status	Active
Class	PLASTIC
Category	Green
Pb (Lead) Free	Yes
Pb Free Category	e3 Sn
Mark	F
Package Type	SSOP
Lead Count	48
Length	15.9 mm
Width	7.5 mm
Thickness	2.3 mm
Pitch	0.64 mm
Tube / Tray	TUBE
Quantity per Tube/Tray	30
Quantity per Reel	1000
Moisture Sensitivity Level (MSL)	1
Moisture	Unlimited@<30C/85%

Exposure RH
Floor Life
Peak Reflow Temperature 260°C
Rebake Conditions NA
Related Package Documents [view documents](#)

DOCUMENTS

Type	Title	Size	Revision Date
Misc	PC Clocks Contact Info	61 KB	05/29/2007
Product Change Notice	PCN# : TB1010-01 Remove Country of Origin from Package Bottom	677 KB	11/21/2010
	PCN# : A0807-02R1 Copper Bond Wire for SSOP, SOIC and TSSOP	144 KB	01/06/2009
	PCN# : A0807-02 Copper Bond Wire for SSOP, SOIC and TSSOP	144 KB	07/30/2008
Product Delete Notice	PDN# : M-07-01 SELECTED DIMM PRODUCT DISCONTINUANCE NOTICE	144 KB	07/24/2007

DISTRIBUTOR INVENTORY

Part	Distributor	Qty	Date	RFQ	Order
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No matches found.

CONTACTS

Sales Offices

▶ [Sales Offices and authorized distributors](#)

Technical Support

Clock Help

▶ [WWW: Clock Help](#)

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